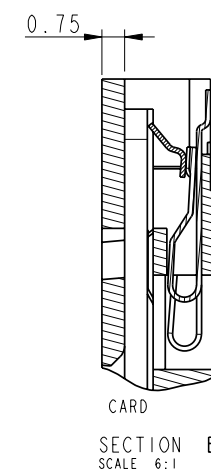
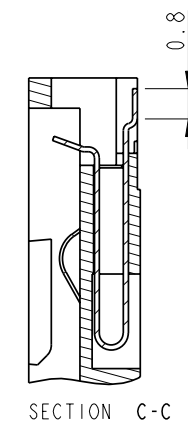
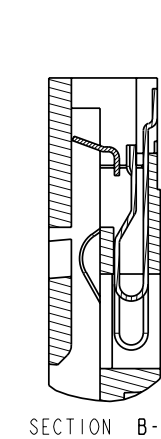
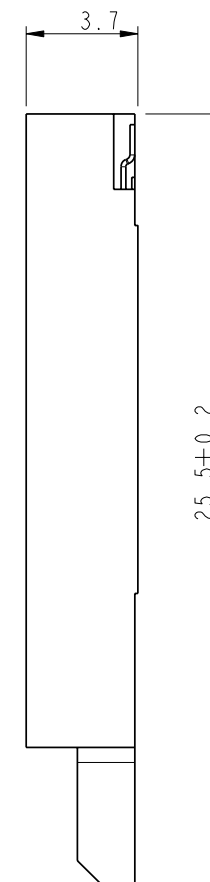
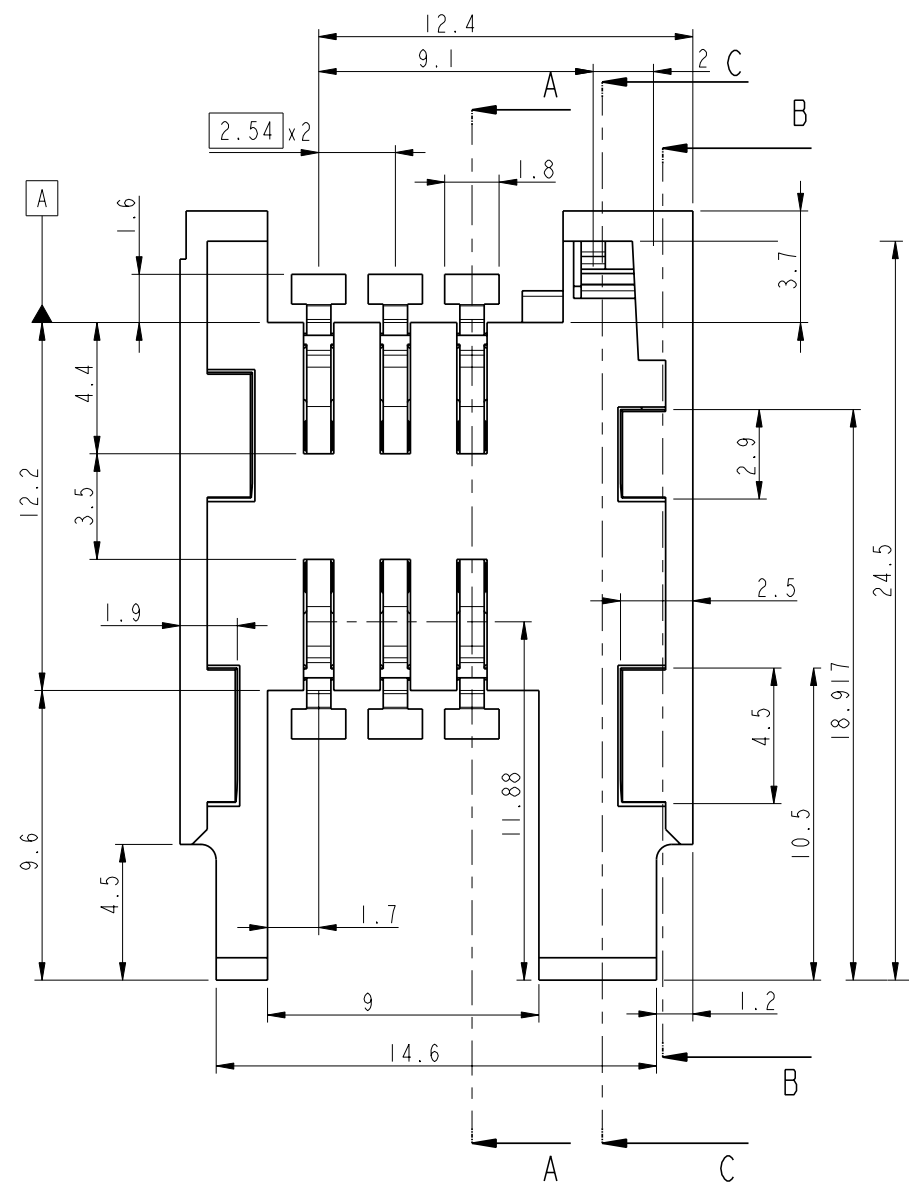
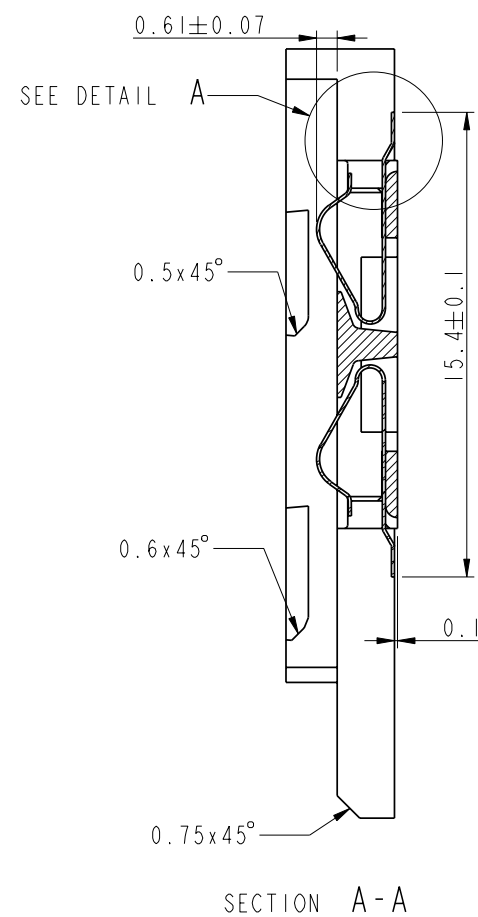
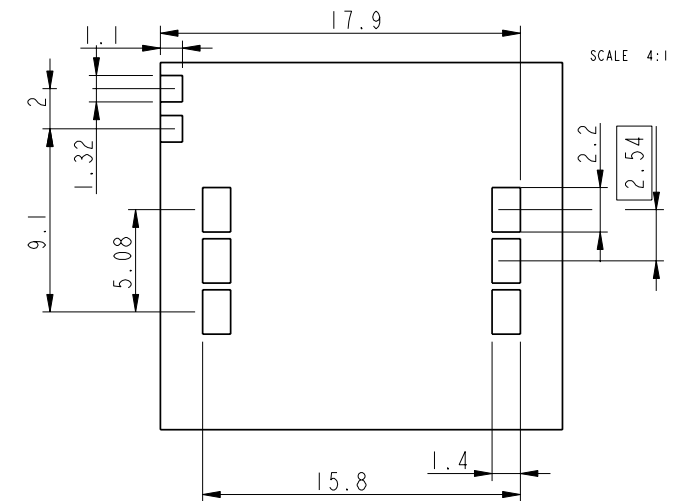
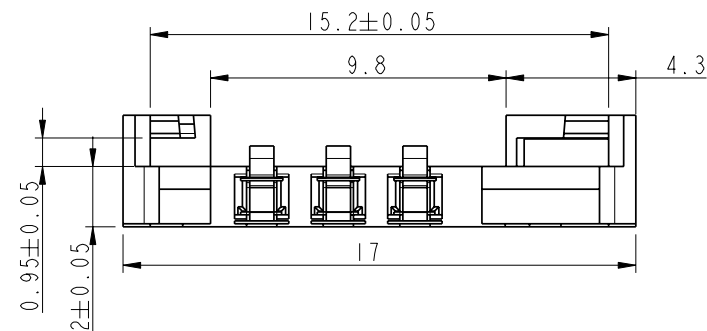
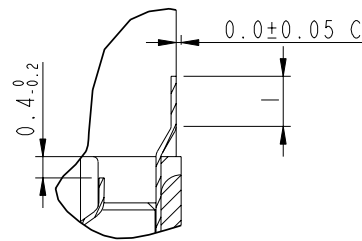


PART NUMBER
7111S1615A02
LEAD FREE VERSION
7111S1615A02LF

DETAIL A
SCALE 10:1



DETAIL OF SWITCH

LEAD FREE VERSION:

"This product meets European Union Directives and other country regulations as described in GS-22-008"

The housing will withstand exposure to 260°C peak temperature for 10 seconds in a convection reflow oven.

PROCESSING

PROCESSING

Ni	2 micrometer
Gold	2.5 micrometer
Solder tail: SnPb	2.5 micrometer (for leaded version)
matte tin	2.5 micrometer (for lead free version)

rev	ecn no	dr	date
01	-	JBB	1998-09-0
A	-	-	2001-12-0
B	-	MPE	2002-03-0
C	LS2025	MPE	2002-05-0
D	105-0167	NT	2005/09/2
E	106-0121	DTK	2006/07/1

www.fciconnect.com			surface -  ISO 1302		tolerance std ISO 406 ISO 1101		projection 		mm 		
			TOLERANCES UNLESS OTHERWISE SPECIFIED								
Dr	BERNARDET	1998/09/02	ANGULAR	LINEAR	0.X		±		size A2	Scale 6:1	
Eng	ODIC	1998/09/02			0.XX		±				
Chr	DILIP THOMAS	2006/07/18	0°	±°	0.XXX		±		ECN	106-0121	
Appr	K.V.SIVADAS	2006/07/18	Product family				MOBILE IO		Spec ref	--	
			SIMCARD CONNECTOR WITH SWITCH						VJW_54479		Rev. E
TYPE S16			catalog no				SFF NOTES		CUSTOMER		sheet 1 of 1